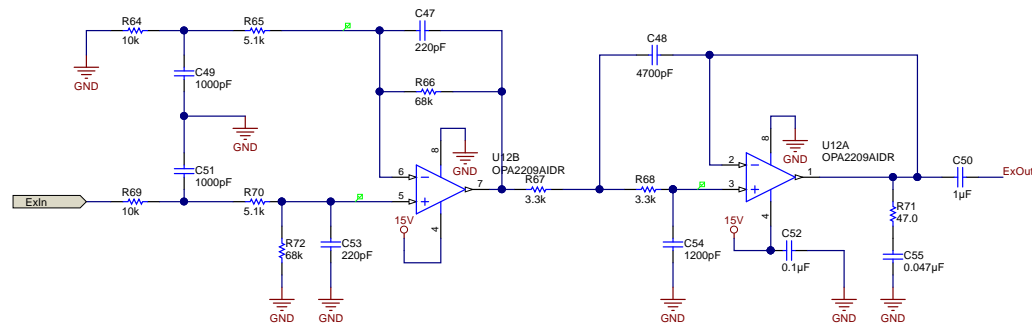
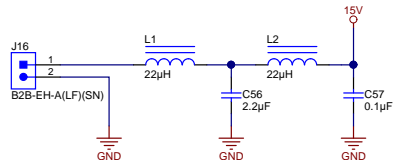
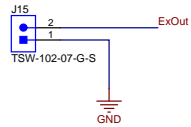


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Orderable: TBD	Designed for: Public Release	Mod. Date: 8/11/2017
TID #: TIDM-1008	Project Title: EnDat 2.2 ABS Enc Master w/ C2000 MCUs	
Number: TIDM-1008 Rev: E2	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: TIDM-1008_PowerAndInterface_SchDoc	Size: B
Engineer: Subrahmanya Bharath	Contact: http://www.ti.com/support	http://www.ti.com



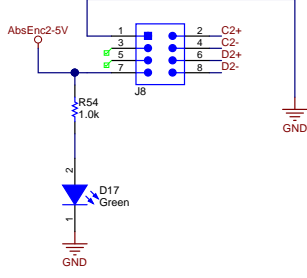
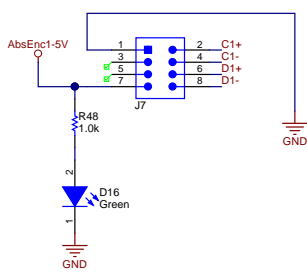
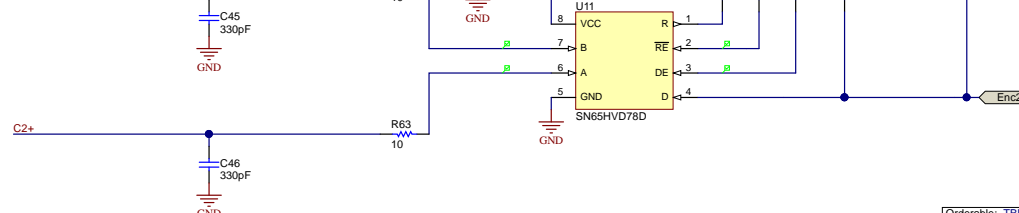
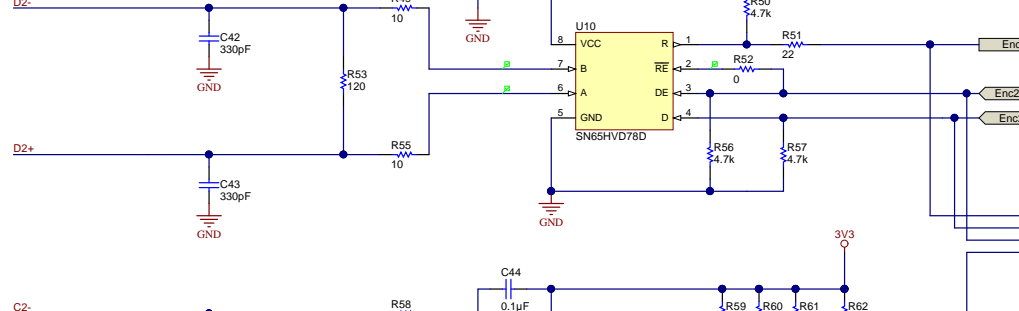
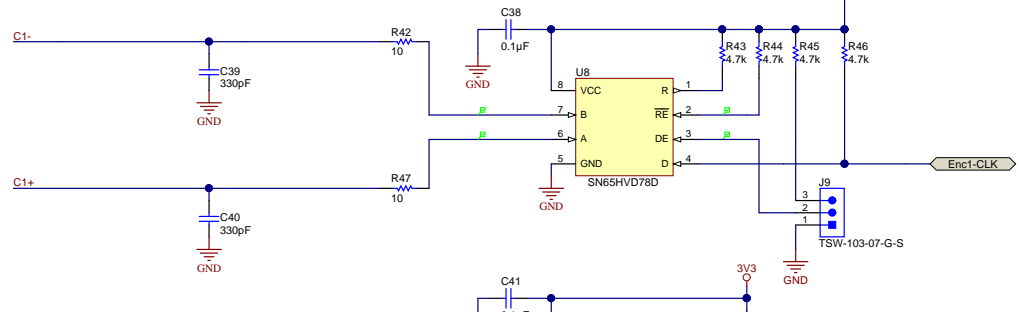
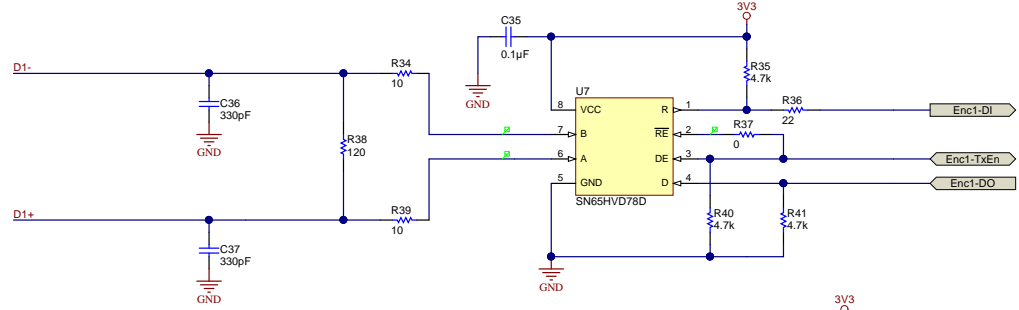
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TID #: TIDM-1008	Project Title: EnDat 2.2 ABS Enc Master w/ C2000 MCUs	
Number: TIDM-1008 Rev: E2	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: TIDM-1008_Resolver_SchDoc	Size: B
Engineer: Subrahmanya Bharath	Contact: http://www.ti.com/support	





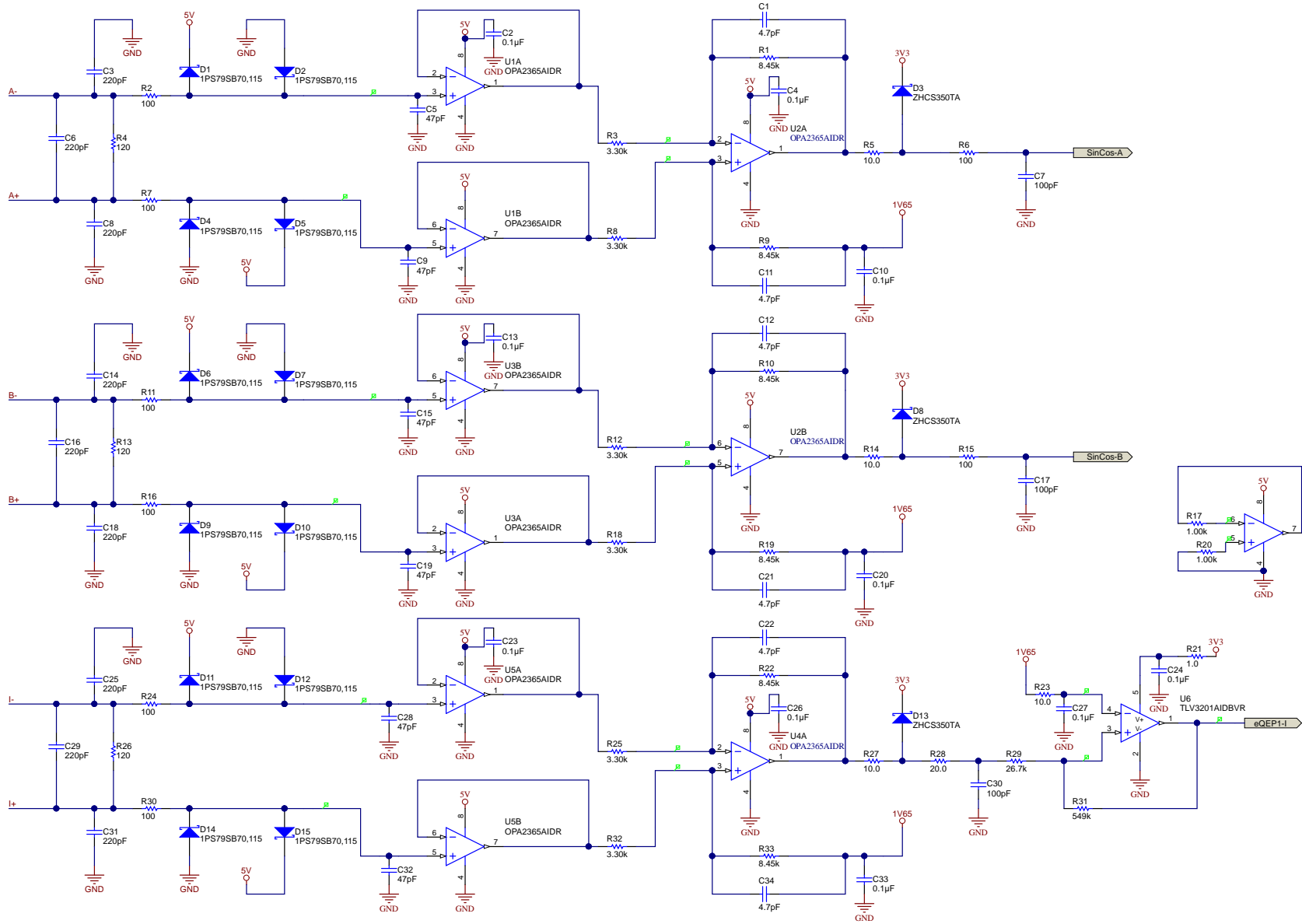
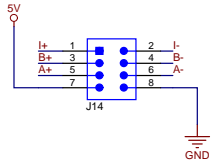
Orderable: TBD	Designed for: Public Release	Mod. Date: 8/11/2017
TID #: TIDM-1008	Project Title: EnDat 2.2 ABS Enc Master w/ C2000 MCUs	
Number: TIDM-1008 Rev: E2	Sheet Title:	
SVN Rev. Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: TIDM-1008_AbsEnc_SchDoc	Size: B
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worth testing, try removing C3
C8 (can cause differential issues
if not exactly matched). A and B
priority.
same goes for other pairs

alternative: split 120 ohm into
x2 60 ohm w/ cap in the middle



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TID #: TIDM-1008	Project Title: EnDat 2.2 ABS Enc Master w/ C2000 MCUs	
Number: TIDM-1008 Rev: E2	Sheet Title:	
SVN Rev. Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: TIDM-1008_SinCos.SchDoc	Size: B
Engineer: Subrahmanya Bharathi	Contact: http://www.ti.com/support	



1 2 3 4 5 6

A

A

PCB Number: TIDM-1008
PCB Rev: 002

PCB
LOGO
Pb-Free Symbol

PCB
LOGO
Logo4

B

B

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

D

D

Orderable: TBD	Designed for: Public Release	Mod. Date: 8/11/2017
TID #: TIDM-1008	Project Title: EnDat 2.2 ABS Enc Master w/ C2000 MCUs	
Number: TIDM-1008 Rev: E2	Sheet Title:	Sheet: 3 of 3
SVN Rev. Version control disabled	Assembly Variant: [No Variations]	Size: B
Drawn By:	File: TIDM-1008_Hardware.SchDoc	http://www.ti.com
Engineer: Subrahmanya Bharathi	Contact: http://www.ti.com/support	© Texas Instruments 2017



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1 2 3 4 5 6

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